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ENFORMATION DISCLOSURE					Filing Date		/larch 24, 2000			
	STATEMENT BY APPLICANT					First Named Inventor S		hunpei YAMAZAKI et al.		
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Examiner Initials	Cite No.1	Office ³	oreign Patent Document Kind Code ^a Number ⁴ (if known)		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	7⁵	
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Examiner	/Sara Crane/	Date	08/30/2006 9/13/2026
Signature	/bara cranc/	Considered	08/30/2006,9/13/2006

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				Filing Date		March 24, 2000		
6 2 \				First Named Inventor		Shunpei YAMAZAKI et	al.	
Sone Three				Group Art Unit		2811		
ତ୍ରା				Examiner Name		Sara W. Crane		
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